



AMENDMENT TRANSMITTAL LETTER

Docket No.
TESSERA 3.0-139 DIV

Application No.
09/854,269

Filing Date
May 11, 2001

Examiner
Monica Lewis

Art Unit
2822

Applicant(s): Thomas H. DiStefano

Invention: MICROELECTRONIC PACKAGES WITH ELONGATED SOLDER INTERCONNECTIONS

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	7	- 20 =		x	0.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

☒ Large Entity

☐ Small Entity

☒ No additional fee is required for this amendment.

☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.

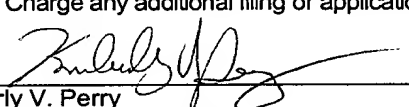
☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.

☐ Payment by credit card. Form PTO-2038 is attached.

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Kimberly V. Perry
Attorney Reg. No.: 43,612

Dated: November 7, 2002

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Box Non-Fee Amendment, Commissioner for Patents, Washington, DC 20231, on the date shown below.

Dated: November 7, 2002

Signature: 

(Kimberly V. Perry)



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Dated: November 7, 2002 Signature: Kimberly V. Perry

(Kimberly V. Perry)

Docket No.: TESSERA 3.0-139 DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Thomas H. DiStefano

Application No.: 09/854,269

Filed: May 11, 2001

For: MICROELECTRONIC PACKAGES WITH
ELONGATED SOLDER
INTERCONNECTIONS

Commissioner for Patents
Washington, DC 20231

Group Art Unit: 2822

Examiner: *Monica Lewis*

*5# and a
drug corrections*

*11/25/02
RECEIVED
NOV 21 2002
TECHNOLOGY CENTER 2820
Brown*

AMENDMENT

Dear Madam:

In response to the Official Action mailed May 2002, in which claims 1-7 were rejected, applicants submit the following amendments and remarks.

IN THE TITLE

CLEAN COPY OF AMENDED TITLE:

MICROELECTRONIC PACKAGES WITH ELONGATED SOLDER
INTERCONNECTIONS

IN THE DRAWINGS

Please amend Figs. 5, 11 and 13 as shown in the attached red-lined drawings.

IN THE CLAIMS

CLEAN COPY OF AMENDED CLAIMS:

1. (Amended) A packaged microelectronic element comprising:

(a) a microelectronic element having a front surface with contact pads thereon;

a

sub B1